



Material Content Data Sheet



Sales Product Name		BSS139 H6327		Issued		29. August 2013			
MA#		MA000932404							
Package		PG-SOT23-3-5		Weight*		9.35 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.004	0.05		472		
	noble metal	gold	7440-57-5	0.017	0.18		1829		
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20724	23025	
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		966		
	inorganic material	silicon	7440-21-3	0.001	0.01		64		
	non noble metal	titanium	7440-32-6	0.003	0.03		322		
	non noble metal	copper	7440-50-8	3.000	32.08	32.22	320752	322104	
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	784	784	
	encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6077	
		plastics	epoxy resin	-	1.222	13.07		130652	
	inorganic material	silicondioxide	60676-86-0	4.405	47.08	60.76	470955	607684	
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15997	15997	
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30406	30406	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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